

ABSTRACT OF THE INVENTION

A dicing die bonding adhesive film for disposition between a semiconductor silicon wafer and a dicing support tape comprises a Layer-1 adhesive, which comes in contact with the dicing tape, and a Layer-2 adhesive, which comes in contact with the silicon semiconductor wafer, in which the adhesion of Layer 2 to the silicon wafer is higher than the adhesion of Layer 1 to the dicing tape by at least 0.1N/cm.